

10030104\_CLS

Most Frequently Occurring Classifications of Patents Returned  
From A Search of 10030104 on August 05, 2003

Original Classifications

4 382/147  
2 324/158.1  
2 324/537  
2 324/754  
2 324/758  
2 361/792

Cross-Reference Classifications

5 257/E23.067  
5 348/126  
4 257/698  
4 324/754  
3 257/700  
3 257/E23.069  
3 324/537  
3 356/237.5  
3 382/147  
3 382/151  
2 174/261  
2 257/693  
2 257/737  
2 257/E23.004  
2 257/E23.068  
2 324/158.1  
2 324/757  
2 324/758  
2 324/765  
2 324/95  
2 356/394  
2 356/398  
2 361/777

Combined Classifications

7 382/147  
6 324/754  
5 257/E23.067  
— 5 324/537  
5 348/126  
4 257/698  
4 324/158.1  
4 324/758  
3 174/261  
3 257/693

10030104\_CLS

3 257/700  
3 257/E23.069  
3 324/765  
3 356/237.5  
3 356/394  
3 382/151  
2 174/260  
2 250/559.34  
2 257/737  
2 257/E23.004  
2 257/E23.068  
2 324/757  
2 324/95  
2 356/398  
2 361/777  
2 361/792

10030104\_CLSTITLES

Titles of Most Frequently Occurring Classifications of Patents Returned

From A Search of 10030104 on August 05, 2003

7 382/147 (4 OR, 3 XR)  
 Class 382 : IMAGE ANALYSIS  
 382/100 APPLICATIONS  
 382/141 .Manufacturing or product inspection  
 382/145 ..Inspection of semiconductor device or printed  
 circuit board  
 382/147 ...Inspecting printed circuit boards

6 324/754 (2 OR, 4 XR)  
 Class 324 : ELECTRICITY: MEASURING AND TESTING  
 324/500 FAULT DETECTING IN ELECTRIC CIRCUITS AND OF  
 ELECTRIC COMPONENTS  
 324/537 .Of individual circuit component or element  
 324/754 ..With probe elements

5 257/E23.067 (0 OR, 5 XR)  
 Class 257 : ACTIVE SOLID-STATE DEVICES  
 257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR  
 SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)  
 257/E23.01 .Arrangements for conducting electric current  
 to or from solid-state body in operation  
 , e.g., leads,  
 terminal arrangements (EPO)  
 257/E23.023 ..Consisting of soldered or bonded  
 constructions (EPO)  
 257/E23.06 ...Leads, i.e., metallizations or lead-frames  
 on insulating substrates, e.g., chip carriers (EPO)  
 257/E23.067 ....Via connections through substrates, e.g.,  
 pins going through substrate, coaxial cables (EPO)

5 324/537 (2 OR, 3 XR)  
 Class 324 : ELECTRICITY: MEASURING AND TESTING  
 324/500 FAULT DETECTING IN ELECTRIC CIRCUITS AND OF  
 ELECTRIC COMPONENTS  
 324/537 .Of individual circuit component or element

5 348/126 (0 OR, 5 XR)  
 Class 348 : TELEVISION  
 348/61 SPECIAL APPLICATIONS

10030104\_CLSTITLES

348/125 .Flaw detector  
348/126 ..Of electronic circuit chip or board

4 257/698 (0 OR, 4 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/688 .With large area flexible electrodes in press  
contact with opposite sides of active sem

iconductor chip

and surrounded by an insulating element,

e.g., ring

257/690 .With contact or lead

257/698 ..With specific electrical feedthrough  
structure

4 324/158.1 (2 OR, 2 XR)

Class 324 : ELECTRICITY: MEASURING AND TESTING

324/158.1 MISCELLANEOUS

4 324/758 (2 OR, 2 XR)

Class 324 : ELECTRICITY: MEASURING AND TESTING

324/500 FAULT DETECTING IN ELECTRIC CIRCUITS AND OF  
ELECTRIC COMPONENTS

324/537 .Of individual circuit component or element

324/754 ..With probe elements

324/758 ...Probe alignment or positioning

3 174/261 (1 OR, 2 XR)

Class 174 : ELECTRICITY: CONDUCTORS AND INSULATORS

174/68.1 CONDUITS, CABLES OR CONDUCTORS

174/250 .Preformed panel circuit arrangement (e.g.,  
printed circuit)

174/261 ..With particular conductive connection (e.g.,  
crossover)

3 257/693 (1 OR, 2 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/688 .With large area flexible electrodes in press  
contact with opposite sides of active se

miconductor chip

and surrounded by an insulating element,

e.g., ring

257/690 .With contact or lead

257/692 ..With particular lead geometry

257/693 ...External connection to housing

3 257/700 (0 OR, 3 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/688 .With large area flexible electrodes in press

10030104\_CLSTITLES

iconductor chip  
 contact with opposite sides of active sem  
 and surrounded by an insulating element,  
 e.g., ring  
 257/690 .With contact or lead  
 257/700 ..Multiple contact layers separated from each  
 other by insulator means and forming part o  
 f a package or  
 housing (e.g., plural ceramic layer package  
 )

3 257/E23.069 (0 OR, 3 XR)  
 Class 257 : ACTIVE SOLID-STATE DEVICES  
 257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR  
 SEMICONDUCTOR OR OTHER SOLID-STATE DEV  
 ICES (EPO)  
 257/E23.01 .Arrangements for conducting electric current  
 to or from solid-state body in operatio  
 n, e.g., leads,  
 terminal arrangements (EPO)  
 257/E23.023 ..Consisting of soldered or bonded  
 constructions (EPO)  
 257/E23.06 ...Leads, i.e., metallizations or lead-frames  
 on insulating substrates, e.g., chip carr  
 iers (EPO)  
 257/E23.068 ....Additional leads joined to metallizations  
 on insulating substrate, e.g., pins, bumps  
 , wires, flat  
 leads (EPO)  
 257/E23.069 .....Spherical bumps on substrate for external  
 connection, e.g., ball grid arrays (BGA) (E  
 PO)

3 324/765 (1 OR, 2 XR)  
 Class 324 : ELECTRICITY: MEASURING AND TESTING  
 324/500 FAULT DETECTING IN ELECTRIC CIRCUITS AND OF  
 ELECTRIC COMPONENTS  
 324/537 .Of individual circuit component or element  
 324/765 ..Test of semiconductor device

3 356/237.5 (0 OR, 3 XR)  
 Class 356 : OPTICS: MEASURING AND TESTING  
 356/237.1 INSPECTION OF FLAWS OR IMPURITIES  
 356/237.2 .Surface condition  
 356/237.5 ..On patterned or topographical surface (e.g.,  
 wafer, mask, circuit board)

3 356/394 (1 OR, 2 XR)

10030104 CLSTITLES

Class 356 : OPTICS: MEASURING AND TESTING  
 356/388 BY CONFIGURATION COMPARISON  
 356/394 .With comparison to master, desired shape, or  
 reference voltage

3 382/151 (0 OR, 3 XR)  
 Class 382 : IMAGE ANALYSIS  
 382/100 APPLICATIONS  
 382/141 .Manufacturing or product inspection  
 382/145 ..Inspection of semiconductor device or printe

d

circuit board  
 382/151 ...Alignment, registration, or position  
 determination

2 174/260 (1 OR, 1 XR)  
 Class 174 : ELECTRICITY: CONDUCTORS AND INSULATORS  
 174/68.1 CONDUITS, CABLES OR CONDUCTORS  
 174/250 .Preformed panel circuit arrangement (e.g.,  
 printed circuit)  
 174/260 ..With electrical device.

2 250/559.34 (1 OR, 1 XR)  
 Class 250 : RADIANT ENERGY  
 250/200 PHOTOCELLS; CIRCUITS AND APPARATUS  
 250/559.01 .With circuit for evaluating a web, strand,  
 strip, or sheet  
 250/559.29 ..Measuring position  
 250/559.34 ...Lead or wire bond inspection

2 257/737 (0 OR, 2 XR)  
 Class 257 : ACTIVE SOLID-STATE DEVICES  
 257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD  
 257/737 .Bump leads

2 257/E23.004 (0 OR, 2 XR)  
 Class 257 : ACTIVE SOLID-STATE DEVICES  
 257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR  
 SEMICONDUCTOR OR OTHER SOLID-STATE DEVICE

S (EPO)

257/E23.003 .Mountings, e.g., nondetachable insulating  
 substrates (EPO)  
 257/E23.004 ..Characterized by shape (EPO)

2 257/E23.068 (0 OR, 2 XR)  
 Class 257 : ACTIVE SOLID-STATE DEVICES  
 257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR  
 SEMICONDUCTOR OR OTHER SOLID-STATE DEVI

10030104\_CLSTITLES

CES (EPO)

257/E23.01 .Arrangements for conducting electric current  
to or from solid-state body in operation  
, e.g., leads,  
terminal arrangements (EPO)  
257/E23.023 ..Consisting of soldered or bonded  
constructions (EPO)  
257/E23.06 ....Leads, i.e., metallizations or lead-frames  
on insulating substrates, e.g., chip carri  
ers (EPO)  
257/E23.068 ....Additional leads joined to metallizations  
on insulating substrate, e.g., pins, bumps,  
wires, flat  
leads (EPO)

2 324/757 (0 OR, 2 XR)

Class 324 : ELECTRICITY: MEASURING AND TESTING  
324/500 FAULT DETECTING IN ELECTRIC CIRCUITS AND OF  
ELECTRIC COMPONENTS  
324/537 .Of individual circuit component or element  
324/754 ..With probe elements  
324/757 ...Probe contact enhancement

2 324/95 (0 OR, 2 XR)

Class 324 : ELECTRICITY: MEASURING AND TESTING  
324/76.11 MEASURING, TESTING, OR SENSING ELECTRICITY, PE

R

SE  
324/95 .With waveguide or long line

2 356/398 (0, OR, 2 XR)

Class 356 : OPTICS: MEASURING AND TESTING  
356/388 BY CONFIGURATION COMPARISON  
356/398 .With object being compared and light beam  
moved relative to each other (e.g., scannin

g)

2 361/777 (0 OR, 2 XR)

Class 361 : ELECTRICITY: ELECTRICAL SYSTEMS AND DEVICES  
361/600 HOUSING OR MOUNTING ASSEMBLIES WITH DIVERSE  
ELECTRICAL COMPONENTS  
361/679 .For electronic systems and devices  
361/748 ..Printed circuit board  
361/760 ...Connection of components to board  
361/777 ....By specific pattern on board

2 361/792 (2 OR, 0 XR)

10030104 CLSTITLES

Class 361 : ELECTRICITY: ELECTRICAL SYSTEMS AND DEVICES

361/600 . HOUSING OR MOUNTING ASSEMBLIES WITH DIVERSE  
ELECTRICAL COMPONENTS

361/679 .For electronic systems and devices

361/748 ..Printed circuit board

361/784 ...Plural

361/792 ....Plural contiguous boards